Please note that Cypress is an Infineon Technologies Company.
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

Cypress Semiconductor
Board/Module Qualification Report

QTP# 194106 VERSION**
October 2019

SIGMATRON BOARD ASSEMBLY	
CYBLE-416045-02	**EZ-BLE™ Creator Module**

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
194106	Qualification of New BLE Module CYBLE-416045-02 with New Silicon Device CY8C6347BZI-BLD53	Oct. 2019

PRODUCT DESCRIPTION	
Qualification Purpose: Qualify New BLE Module CYBLE-416045-02 with New Silicon Device CY8C6347BZI-BLD53	
Marketing Part #:	CYBLE-416045-02
Device Description:	BLE Modules
Cypress Division:	MCU and Connectivity Division (MCD)
Board Material:	FR4
Board Dimension:	14x18.5mm
Board Layers:	4
Surface Finish:	ENIG
Name/Location of Assembly (prime) facility:	Sigmatron/Wujiang, China

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Acoustic Microscopy	JEDEC JSTD-020	P
High Temperature Operating Life	MIL-STD 202 Method 108, Dynamic Operating Condition, Vcc Max = 3.3V, 85C	P
High Temperature Storage	MIL-STD 202 Method 103, 90C, no bias	P
Low Temperature Operating Life	MIL-STD 202 Method 108, Dynamic Operating Condition, Vcc Max = 3.3V, -40C	P
Low Temperature Storage	MIL-STD 202 Method 103, -50C, no bias	P
Mechanical Shock	MIL-STD 202 Method 213	P
Temperature Cycle	MIL-STD 202 Method 107, -40C to 85 C	P
Temperature Humidity	MIL-STD 202 Method 106, 95C, 85%RH	P
Vibration	MIL-STD 202 Method 204	P

Reliability Test Data

QTP #: 194106

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC							
CYBLE-416045-02	0	0	SIGMATRON	COMP	5	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (85C, 3.3V, Vcc Max)							
CYBLE-416045-02	0	0	SIGMATRON	168	22	0	
STRESS: HIGH TEMP STORAGE, 90C							
CYBLE-416045-02	0	0	SIGMATRON	168	15	0	
STRESS: LOW TEMP DYNAMIC OPERATING LIFE, (-40C, 3.3V, Vcc Max)							
CYBLE-416045-02	0	0	SIGMATRON	168	22	0	
STRESS: LOW TEMPERATURE STORAGE, -50C							
CYBLE-416045-02	0	0	SIGMATRON	168	15	0	
STRESS: MECHANICAL SHOCK							
CYBLE-416045-02	0	0	SIGMATRON	COMP	5	0	
STRESS: TC COND. – 40C TO 85C							
CYBLE-416045-02	0	0	SIGMATRON	100	15	0	
STRESS: TEMPERATURE HUMIDITY, 95C/85%RH							
CYBLE-416045-02	0	0	SIGMATRON	168	15	0	
STRESS: VIBRATION							
CYBLE-416045-02	0	0	SIGMATRON	COMP	5	0	

Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	6703205	JYF	Initial spec release.